Chemicals contained in products

EPSON
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Package-type

Epson Package name ; **QFP8-208PIN-S1**
JEITA Package name ; **P-QFP208-2828-0.50**
Terminal plating ; **Lead(Pb) Free**
Weight ; **5.74** [g]*Note1

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2 [mg]	[ppm]	Application
IC Die	IC Die	164	Silicon	7440-21-3	164	999894	Base material
			Boron	7440-42-8	0.0003	2	Dopant
			Phosphorus	7723-14-0	0.0008	5	Dopant
			Aluminum	7429-90-5	0.003	20	Metalization
			Arsenic *Note3	7440-38-2	0.0008	5	Dopant
			Fluorine *Note3	7782-41-4	0.0003	2	Dopant
			Titanium *Note3	7440-32-6	0.003	20	Metalization
			Molybdenum *Note3	7439-98-7	0.003	20	Metalization
			Tungsten *Note3	7440-33-7	0.005	30	Metalization
			Cobalt *Note3	7440-48-4	0.0003	2	Metalization
	Stress buffer coat	3.3	Polyimide	-	3.3	1000000	Stress buffer coat *Note4
Package	Die Bonding material	7.2	Silver	7440-22-4	4.9	677732	Base material
			Epoxy resin	-	1.50	207469	Adhesive
			Phenol resin	-	0.54	74689	Adhesive
			Inorganic powder	-	0.29	40111	Additive
	Lead Frame Plating	49	Tin	7440-31-5	48	979716	Solder
			Bismuth	7440-69-9	1.0	20284	Solder
	Lead Frame	751	Copper	7440-50-8	710	945125	Conductor
			Silver	7440-22-4	3.7	4928	Inner lead plating
			Others *Note5	-	38	49947	Additive
	Bonding Wire	12	Gold	7440-57-5	12	1000000	Conductor
	Mold resin	4757	Epoxy resin	-	238	49988	Base material
			Antimony trioxide	1309-64-4	19	3994	Flame retardant
			Halogenated compound(Brominations epoxy)	-	43	8997	Flame retardant
			Silica	60676-86-0/-	3839	807025	Filler
			Carbon black	1333-86-4	71	14988	Coloring agent
			Hardening chemical(ex:Phenol resin)	-	286	60016	Base material
			Organic phosphorous compound	-	24	5003	Hardening accelerator
			others	-	238	49988	Additive

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.
*Note2 Content data are estimated values based on supplier information and intended levels of content in product.
Actual measurements may vary from these values somewhat.
*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.
*Note4 The stress buffer coat may not be used depending on the individual model.
*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included for the Cu type. And the carbon, silicon, and manganese are included for 42alloy type.